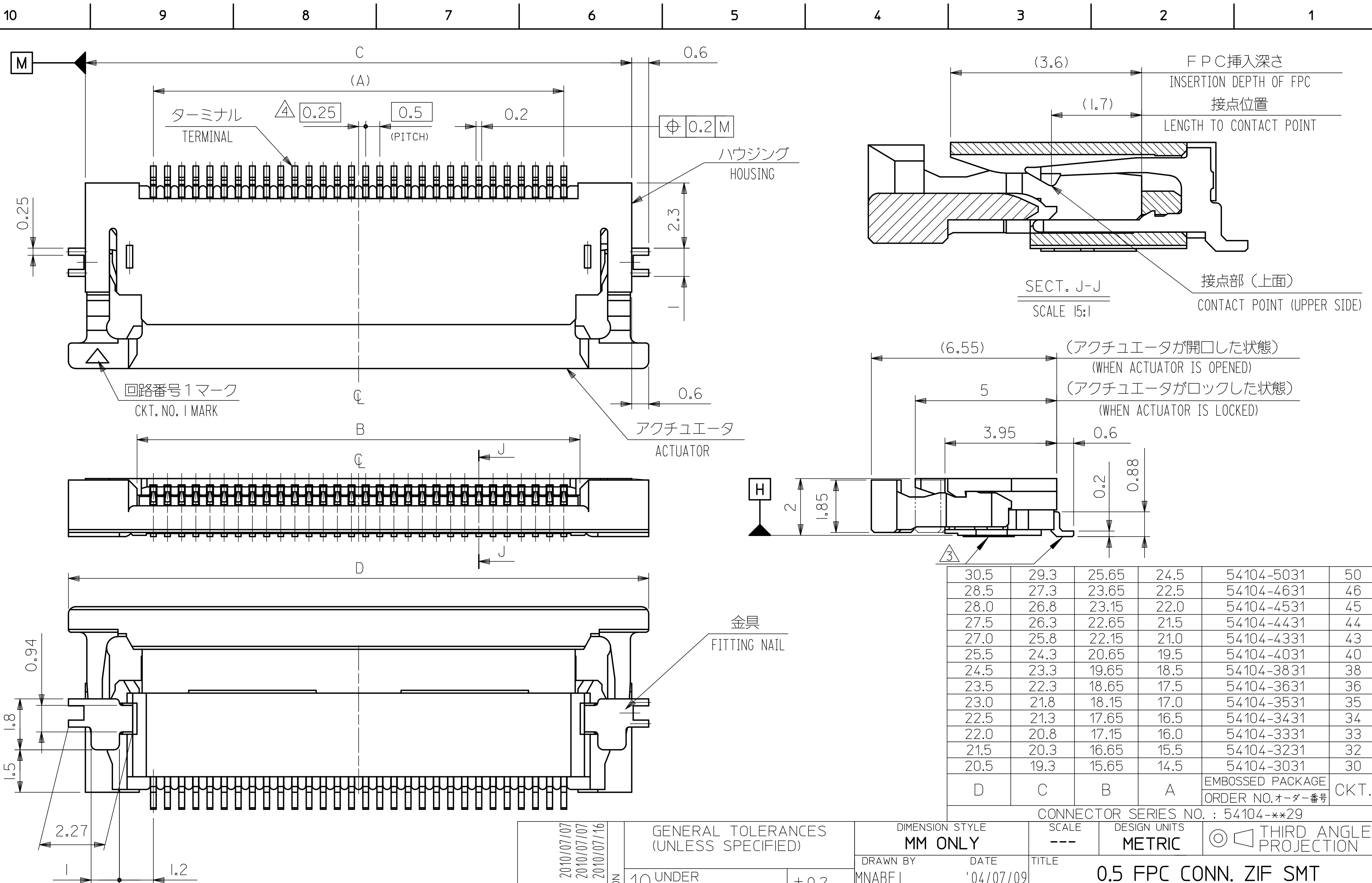


D	C	B	A	EMBOSSED PACKAGE ORDER NO.オーダー番号	CKT.
30.5	29.3	25.65	24.5	54104-5031	50
28.5	27.3	23.65	22.5	54104-4631	46
28.0	26.8	23.15	22.0	54104-4531	45
27.5	26.3	22.65	21.5	54104-4431	44
27.0	25.8	22.15	21.0	54104-4331	43
25.5	24.3	20.65	19.5	54104-4031	40
24.5	23.3	19.65	18.5	54104-3831	38
23.5	22.3	18.65	17.5	54104-3631	36
23.0	21.8	18.15	17.0	54104-3531	35
22.5	21.3	17.65	16.5	54104-3431	34
22.0	20.8	17.15	16.0	54104-3331	33
21.5	20.3	16.65	15.5	54104-3231	32
20.5	19.3	15.65	14.5	54104-3031	30

CONNECTOR SERIES NO. : 54104-**29

REVISED
EC NO: J2011-0041 2010/07/07
DRWN:H.IIJIMA 2010/07/07
CH'KD:H.IIJIMA 2010/07/16
APPR:K.MORIKAWA
E | REV | DESCRIPTION

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

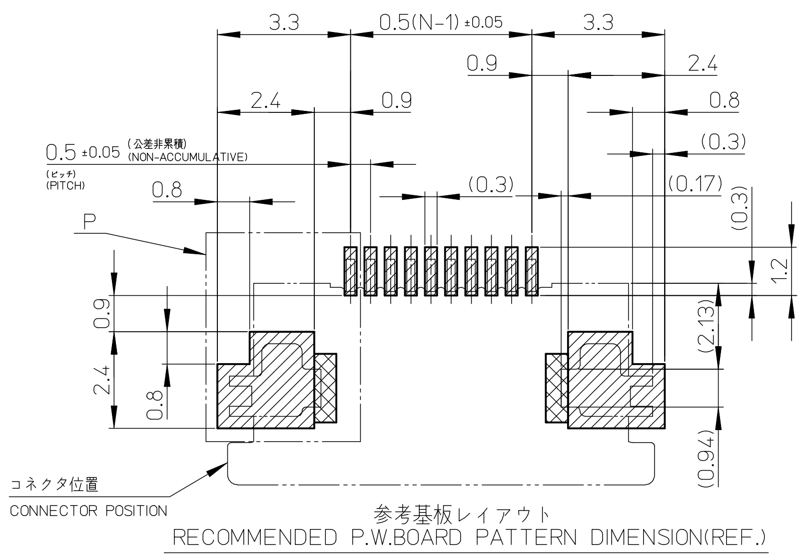
DRAWN BY: MNABEI DATE: '04/07/09
CHECKED BY: KTOJO DATE: '04/07/09
APPROVED BY: NUKITA DATE: '04/07/09

TITLE: 0.5 FPC CONN. ZIF SMT R/A UPPER CONTACT SEPARATED GOLD PLATING

molex MOLEX INCORPORATED

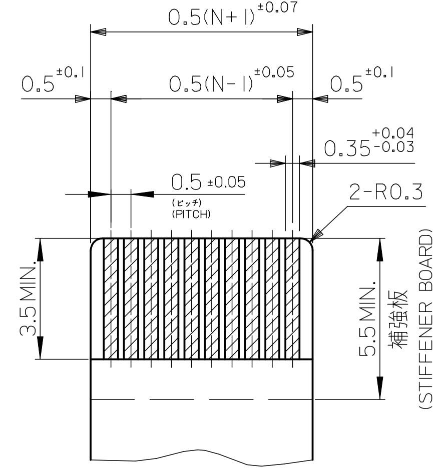
MATERIAL NO.: SEE SHEET 2 OF 2
DOCUMENT NO.: SD-54104-077
SHEET NO.: 1 OF 2
SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



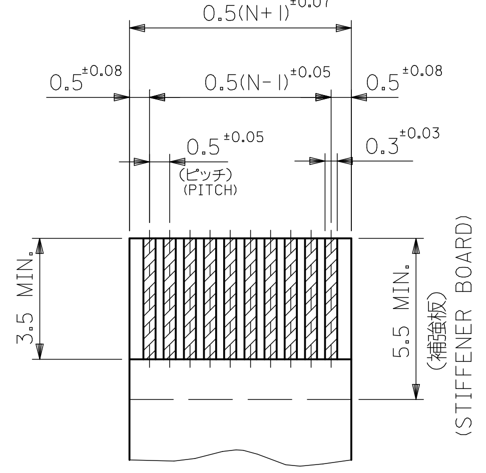
参考基板レイアウト
RECOMMENDED P.W.BOARD PATTERN DIMENSION(REF.)

（マウント面）
(MOUNTING SIDE)



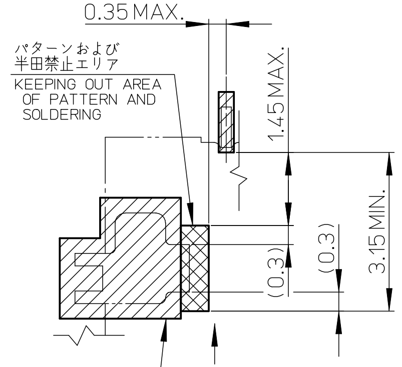
適合金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PLATING
RECOMMENDED DIMENSION

（仕上がり厚さ ： 0.3 ±0.03 ）
(THICKNESS : 0.3±0.03)

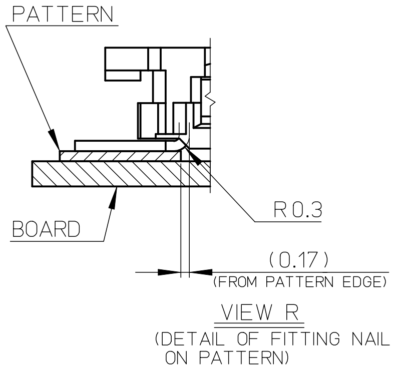


適合金めっきFFC推奨寸法
APPLICABLE FFC OF GOLD PLATING
RECOMMENDED DIMENSION

（仕上がり厚さ ： 0.3 ±0.03 ）
(THICKNESS : 0.3±0.03)



DETAIL P



VIEW R
(DETAIL OF FITTING NAIL
ON PATTERN)

注記 NOTES

1. 使用材料 MATERIAL
   - ハウジング ： 46ナイロン、ガラス充填、UL94V-0、白
   - HOUSING:PA46,GLASS FILLED,UL94V-0,WHITE
   - アクチュエータ：ポリフェニレンサルファイド（PPS）、ガラス充填、UL94V-0、黒
   - ACTUATOR:POLYPHENYLENE SULFIDE,GLASS FILLED,UL94V-0,BLACK
   - ターミナル ： リン青銅(t=0.2) 金メッキ コンタクト部 0.1 MICROMETER MINIMUM
     テール部 0.05 MICROMETER MINIMUM
     ニッケル下地 1.0 MICROMETER MINIMUM
   - TERMINAL PHOS-BRONZE GOLD-PLATING
     CONTACT PORTION : 0.1 MICROMETER MINIMUM
     TAIL PORTION : 0.05 MICROMETER MINIMUM
     NICKEL PLATING : 1.0 MICROMETER MINIMUM
   - 金具 ： リン青銅(t=0.2) 錫メッキ 1.0~3.0 MICROMETER MINIMUM
     ニッケル下地 1.0~3.0 MICROMETER MINIMUM
   - FITTING NAIL : PHOS-BRONZE TIN-PLATING 1.0~3.0 MICROMETER MINIMUM
     OVER NICKEL 1.0~3.0 MICROMETER MINIMUM
2. エンボステープ梱包時はアクチュエータがロックした状態とする。
   IN THE PACKAGE, ACTUATOR OF PART NO.54104-**29 SHOULD BE LOCKED.

△3 ソルダーテール半田付け面のズレ量、および金具半田付け面のズレ量は
基準面 [H] に対し上方向 0.1MAXIMUM、下方向 0.15MAXIMUMとする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM [H]
UPPER DIRECTION : 0.1MAXIMUM, LOWER DIRECTION : 0.15 MAXIMUM.

△4 偶数極に適用。
APPLY FOR EVEN CIRCUIT.

△5 パターンはく離止め金具。
FITTING NAIL FOR PREVENTION OF PEELING
OF P.W.BOARD PATTERN.

6. ELV & RoHS適合品
   ELV AND RoHS COMPLIANT

FPC/FFCについて ：
打ち抜き方向は導体側から補強板側を推奨いたします。
導体部は軟銅箔 35MICROMETER または 50MICROMETERを推奨いたします。
RECOMMENDED PUNCHER DIRECTION
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED CONDUCTOR SPEC
THICKNESS OF SOFT COPPER FOIL
: 35MICROMETERS OR 50MICROMETERS

FPCについて ：
補強フィルム材質はポリイミドを推奨いたします。
接着剤は熱硬化接着剤を推奨いたします。
RECOMMENDED MATERIAL
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

REV	DESCRIPTION		
E	REVISED EC NO: J2011-0041 DRWN:HIIJIMA CH'KD:HIIJIMA APPR:KMORIKAWA	2010/07/07 2010/07/07 2010/07/16	

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	± ---
10 OVER 30 UNDER	± ---
30 OVER	± ---
ANGULAR	± --- °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	SCALE	DESIGN UNITS	
MM ONLY	---	METRIC	THIRD ANGLE PROJECTION

DRAWN BY	DATE	TITLE
MNABEI	'04/07/09	0.5 FPC CONN. ZIF SMT R/A UPPER CONTACT SEPARATED GOLD PLATING
CHECKED BY	DATE	
KTOJO	'04/07/09	
APPROVED BY	DATE	molex MOLEX INCORPORATED
NUKITA	'04/07/09	

MATERIAL NO.	DOCUMENT NO.	SHEET NO.
SEE TABLE	SD-54104-077	2 OF 2

SIZE A3

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